



Initial Product/Process Change Notification

Document #: IPCN24561X

Issue Date: 29 Jun 2022

Title of Change:	Stealth and Hyperfast wafer transfer qualification and wafer size change qualification in onsemi Roznov, Republic Czech from onsemi Bucheon, Korea.	
Proposed First Ship date:	01 Dec 2022 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or norsahida.sahman@onsemi.com , norlailihanim.nordin@onsemi.com , daniel.jeon@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >	
Marking of Parts/ Traceability of Change:	Date Code	
Change Category:	Wafer Size change, Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Transfer	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Bucheon, Korea	None	
onsemi Roznov, Czech Republic		
Description and Purpose:		
This notification is to inform the customers onsemi is qualifying Stealth and Hyperfast wafers in onsemi Roznov, Czech Republic from onsemi Bucheon, Korea. Together with this change wafer size for most of the wafers will also change from 6 inch to 8 inch except for FNA25060 wafer remain as 6 inch wafer size.		
	Before Change Description	After Change Description
Wafer fab	onsemi Bucheon, Korea	onsemi Roznov, Czech Republic
Wafer size	6 inch	8 inch (except for FNA25060)
There is no product marking change as a result of this change.		



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Qualification Plan:

QV DEVICE NAME: RHRG75120

PACKAGE: TO247

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Tj=175°C, 80% max rated V	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 5 min	6000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	

QV DEVICE NAME: FFH75H60S

PACKAGE: TO247

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Tj=175°C, 80% max rated V	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 5 min	6000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	



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QV DEVICE NAME: FGH75T65SQDTL4
PACKAGE: TO247

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta= 175°C, 100% max rated V	1008 hrs
HTGB	JESD22-A108	Ta= 175°C, 100% max rated Vgss	1008 hrs
HTSL	JESD22-A103	Ta= 175°C	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 5 min	6000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	

QV DEVICE NAME: FGA60N65SMD
PACKAGE: TO3PN

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta= 175°C, 100% max rated V	1008 hrs
HTGB	JESD22-A108	Ta= 175°C, 100% max rated Vgss	1008 hrs
HTSL	JESD22-A103	Ta= 175°C	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 5 min	6000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	



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QV DEVICE NAME: FGHL75T65MQD

PACKAGE: TO247

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta= 175°C, 100% max rated V	1008 hrs
HTGB	JESD22-A108	Ta= 175°C, 100% max rated Vgss	1008 hrs
HTSL	JESD22-A103	Ta= 175°C	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 5 min	6000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FGA60N65SMD	FGA60N65SMD
FGHL75T65MQD	FGHL75T65MQD
FSB50550BS	RHRG75120, FFH75H60S
FGH60N60SMD	RHRG75120, FFH75H60S
FGL40N120ANDTU	RHRG75120, FFH75H60S
FGH40T120SMD	RHRG75120, FFH75H60S
NXH240B120H3Q1PG	RHRG75120, FFH75H60S
FFH75H60S	RHRG75120, FFH75H60S
RHRG75120	RHRG75120, FFH75H60S
FSBB10CH120DF	FGH75T65SQDTL4
FNA25060	FGH75T65SQDTL4
ISL9R3060G2	FGH75T65SQDTL4
PCISL9R30120W	FGH75T65SQDTL4
NXH450N65L4Q2F2S1G	FGH75T65SQDTL4
FGH75T65SHDT-F155	FGH75T65SQDTL4
FGH75T65SQDTL4	FGH75T65SQDTL4
PCR8PA5W	FGH75T65SQDTL4